

ABSTRACT OF THE DISCLOSURE

A one system module in which a ceramic PCB and an epoxy PCB are disposed inside a module body and a power element and a signal element are respectively mounted at the upper portion of each PCB, wherein a groove is made at the lower side surface and at the middle side surface of the module body to support the ceramic PCB and the epoxy PCB formed in a two-story structure, and a power pin for receiving a power signal from an external source is mounted on the ceramic PCB and a signal pin for receiving various signals from an external source is mounted on the epoxy PCB. With this one system module, the ceramic PCB and the epoxy PCB can be firmly supported by the groove made on the module body. And, since the power pin and the signal pin are separately disposed on the two PCBs, use of the socket is reduced, so that the area utility of the PCB is increased as well as acquiring a compact module.